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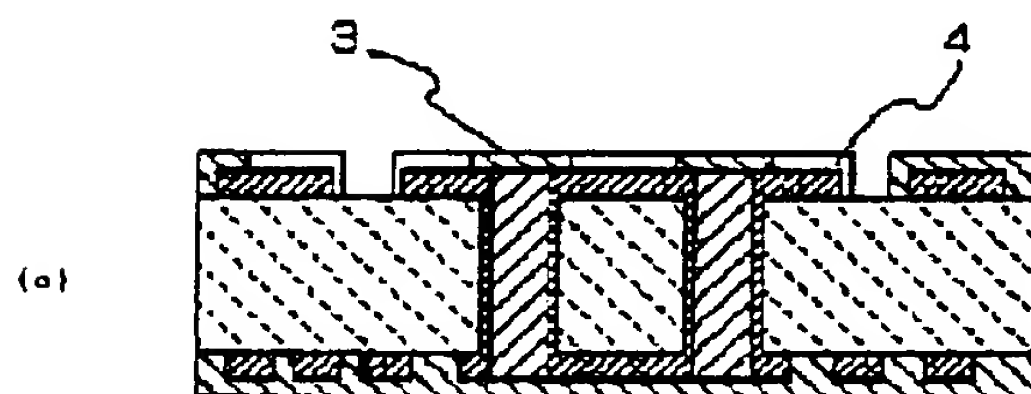
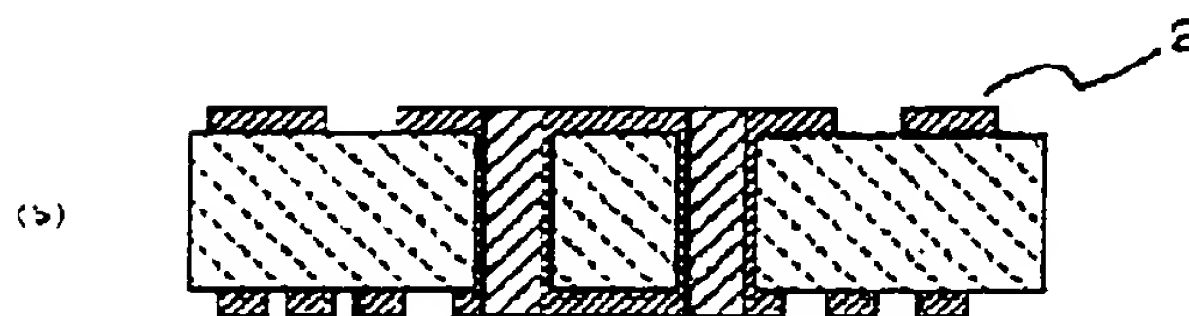
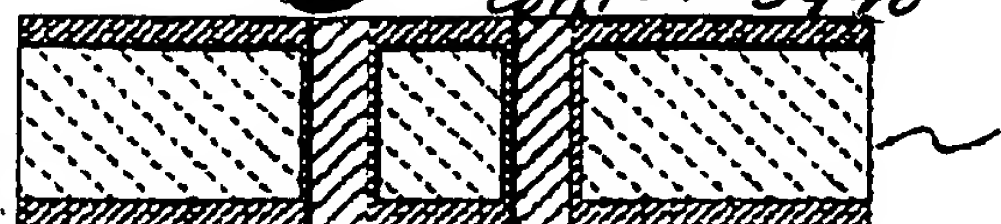
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INVENTOR : NAKAYAMA HAJIME;

INT.CL. : H01L 23/12

TITLE : SUBSTRATE FOR LOADING
SEMICONDUCTOR CHIP AND ITS
MANUFACTURE

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ABSTRACT : PROBLEM TO BE SOLVED: To provide a substrate for loading semiconductor chip, which is superior in the workability of a circuit, by burying resin in a through hole formed in a die pad, and forming a resist pattern for the end part of the through hole so that it blocks the hole.

SOLUTION: The resin of epoxy resin, BT resin and polyimide resin is buried in the through hole formed in the die pad on the substrate 1 loading the semiconductor chip. Then, the resist pattern is formed on the end part of the through hole by using a material for photosensitive solder resist 3 so that the hole is blocked. A surface finishing processing for forming a surface finishing layer 4 of nickel plating and gold plating is executed after the resist pattern for blocking the hole is formed, and the difference of elevation between a resist pattern surface and a surfacial processing surface is set to be not more than 10 μm . Thus, the die bond adhesion stability of a semiconductor can be obtained. Consequently, stable die bond adhesion can be realized without the trouble of the deposition of nonelectrolytic plating.

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